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(71) Applicant (for all designated States except US): **APPLIED MATERIALS, INC.** [US/US]; 3050 Bowers Avenue, Santa Clara, CA 95054 (US).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **YILMAZ, Alpaz** [TR/US]; 491 Danna Court, San Jose, CA 95138 (US).

(74) Agents: **PATTERSON, B. Todd** et al.; Patterson & Sheridan, L.L.P., 3040 Post Oak Blvd., Suite 1500, Houston, TX 77056-6582 (US).

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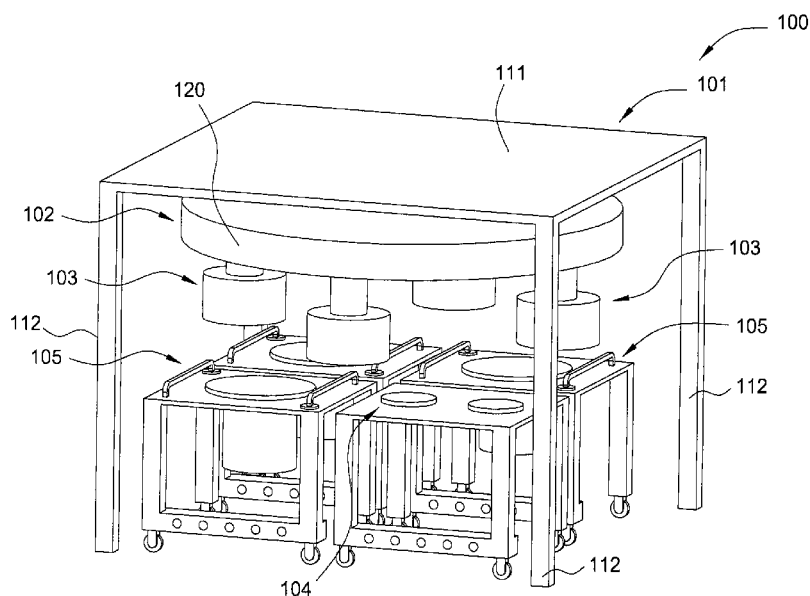


FIG. 1A

(57) Abstract: The present invention generally relates to a polishing system. Particularly, the present invention relates a polishing apparatus having one or more modular polishing stations, and a plurality of polishing heads movably connected to a transferring system.